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APPLICATION NO.	CATION NO. FILING DATE FIRST NAMED INVENTOR		ATTORNEY DOCKET NO.	
		7 [EXAMINER	
			ART UNIT	PAPER NUMBER
		1	DATE MAILED:	

Please find below and/or attached an Office communication concerning this application or proceeding.

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Application No

Applicant(s)

09/045,507

Macintyre

Office Action Summary Examiner

Douglas Wille

Group Art Unit 2814



atters, prosecution as to the merits is closed 453 O.G. 213.			
is/are pending in the application			
is/are withdrawn from consideration			
is/are allowed.			
is/are rejected.			
Claim(s) is/are objected to. Claims are subject to restriction or election requirement			
approved disapproved.			
U.S.C. § 119(a)-(d). ity documents have been			
5 U.S.C. § 119fe			

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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.
- 2. Claims 4, 6, 7, 15 and 17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lin in view of Tsukamoto and Igarashi et al.
- 3. Lin shows a flip chip device (see Figure 5 and column 5, line 15) with a semiconductor chip 12 attached to an interposer board 22. Lin shows the interposer board attached to a PC board with layer of adhesive 36 but does not show a similar attachment between 12 and 22. noting that while it is standard practice (column 2, line 22) it prevents rework. Note that if rework is not as issue, bonding is recommended. Lin also teaches that the thermal coefficient of expansion of the interposer should match that of the die (column 6, line 28). Lin shows vias 24 in the plate 22 with evaporated traces 26 (column 6, line 64) on the plate which connects contacts 16 to vias 24 and solder beads 32 are formed on the surface of 22. I in shows that the metallization 26 c.m be evaporated and if performed after forming the hole it will extend into the holes. In addition a conductive fill is used for the vias (column 6, line 66). Lin does not specify the material of the plate 2 but Tsukamoto shows a similar structure where the plate is a glass ceramic which will

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ceramic plate taught by Tsukamoto to match the TCE of the die and plate and to use the polyimide bond taught by Igarashi et al. to have a known bonding material.

Response to Arguments

- 4. Applicant's arguments filed 3/31/00 have been fully considered but they are not persuasive.
- 5. Applicant states that it would take 500 steps to produce the prior art structure but note that the prior art shows a structure which is completed as a unit and the prior art device shows all the features of the claimed device. Thus the 500 step comment is not pertinent to the present discussion.
- 6. Applicant states that the references, in combination, do not show the claimed invention and that the examiner has not identified a basis for the conclusion of obviousness but if the rejection is reviewed it is seen that all the claimed features are shown by the combination of references and good justification for combining each reference is given.
- 7. Applicant has provided a number of comments related to examiners function which are not here addressed since they do not bear on the rejection shown above.
- 8. Applicant has provided comments related to the number of steps that have to be performed on the wafer but attention is drawn to the fact that the claimed device is shown by the prior art. See the above rejection.

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9. Applicant states that none of the structure of the prior art is formed on the semiconductor wafer but note that the only structure in the claimed device that is on the silicon is a contact which is exactly what is shown by the prior art.

Conclusions

- 10. **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).
- 11. A shortened statutory period for response to this final action is set to expire THREE MONTHS from the date of this action. In the event a first response is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event will the statutory period for response expire later than SIX MONTHS from the date of this final action.
- 12. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Douglas A. Wille whose telephone number is (703) 308-4949.
- 13. Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose number is (703) 308-0956.

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Donald L. Monin, Jr
Primary Examiner

Olik Chaudhuri Supervisory Patent Examiner Art Unit 2814

DAW 1

May 4, 2000